|                                | Parameter                                    | Min. | Тур.  | Max. | Units | Test Conditions  |
|--------------------------------|--|------|-------|------|-------|--|
| BVDSS                          | Drain-to-Source Breakdown Voltage            | -200 | _     | —    | V     | VGS = 0V, ID = -1.0 mA   |
| $\Delta BV_{DSS}/\Delta T_{J}$ | Temperature Coefficient of Breakdown Voltage | _    | -0.22 | —    | V/°C  | Reference to 25°C, I <sub>D</sub> = -1.0 mA  |
| RDS(on)                        | Static Drain-to-Source                       | _    | —     | 0.80 |       | VGS = -10V, ID = -2.4A <sup>(4)</sup>  |
|                                | On-State Resistance                          | —    | —     | 1.68 | Ω     | VGS = -10V, ID = -4.0A   |
| VGS(th)                        | Gate Threshold Voltage                       | -2.0 | —     | -4.0 | V     | $V_{DS} = V_{GS}$ , $I_{D} = -250 \mu A$   |
| gfs                            | Forward Transconductance                     | 2.2  | —     | _    | S (U) | VDS > -15V, IDS = -2.4A ④  |
| IDSS                           | Zero Gate Voltage Drain Current              | —    | —     | -25  |       | VDS = 0.8 x Max Rating, VGS = 0V   |
|                                |  |      |       | -250 | μΑ    | VDS = 0.8 x Max Rating   |
|                                |  |      |       |      |       | VGS = 0V, TJ = 125°C   |
| IGSS                           | Gate-to-Source Leakage Forward               | _    | _     | -100 | nA    | VGS = -20V   |
| IGSS                           | Gate-to-Source Leakage Reverse               | —    | _     | 100  |       | VGS = 20V  |
| Qg                             | Total Gate Charge                            | 14.7 | _     | 34.8 |       | VGS = -10V, ID = -4.0A   |
| Qgs                            | Gate-to-Source Charge                        | 0.8  | —     | 7.0  | nC    | VDS = Max. Rating x 0.5  |
| Qgd                            | Gate-to-Drain ("Miller") Charge              | 5.0  | —     | 17   |       | see figures 6 and 13   |
| td(on)                         | Turn-On Delay Time                           | —    | —     | 50   |       | VDD = -100V, ID = -4.0A,   |
| tr                             | Rise Time                                    | —    | _     | 100  | ns    | $R_{G} = 7.5\Omega$ , $VGS = -10V$   |
| <sup>t</sup> d(off)            | Turn-Off Delay Time                          | —    | —     | 100  | 115   |  |
| tf                             | Fall Time                                    | —    | —     | 80   |       | see figure 10  |
| LD                             | Internal Drain Inductance                    | —    | 5.0   | _    | nH    | Measured from the<br>drain lead, 6mm (0.25<br>in.) from package to<br>center of die.       |
| LS                             | Internal Source Inductance                   | _    | 15.0  |      | пн    | Measured from the<br>source lead, 6mm<br>(0.25 in.) from package<br>to source bonding pad. |
| C <sub>iss</sub>               | Input Capacitance                            |      | 700   |      |       | $V_{GS} = 0V, V_{DS} = -25V$   |
| C <sub>OSS</sub>               | Output Capacitance                           | —    | 200   | —    | pF    | f = 1.0 MHz  |
| C <sub>rss</sub>               | Reverse Transfer Capacitance                 | _    | 40    |      |       | see figure 5   |

# Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

# **Source-Drain Diode Ratings and Characteristics**

|     | Parameter                    |  | Min. | Тур. | Max. | Units | Test Conditions   |
|-----|------------------------------|--|------|------|------|-------|---|
| IS  | Continuous Source Current (I | Body Diode)  | —    | _    | -4.0 | Α     | Modified MOSFET symbol showing the                      |
| ISM | Pulse Source Current (Body I | Diode) ①   |      | _    | -16  |       | integral reverse p-n junction rectifier.                |
| VSD | Diode Forward Voltage        |  | _    | —    | -6.0 | V     | $T_j = 25^{\circ}C$ , $I_S = -4.0A$ , $V_{GS} = 0V$ (4) |
| trr | Reverse Recovery Time        |  | —    | —    | 400  | ns    | Tj = 25°C, IF = -4.0A, di/dt ≤ -100A/μs                 |
| QRR | Reverse Recovery Charge      |  | —    | —    | 4.0  | μC    | V <sub>DD</sub> ≤ -50V ④                                |
| ton | Forward Turn-On Time         | Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_{S}$ + $L_{D}$ . |      |      |      |       |   |

# **Thermal Resistance**

|                    | Parameter           | Min. | Тур. | Max. | Units | Test Conditions      |
|--------------------|---------------------|------|------|------|-------|----------------------|
| RthJC              | Junction-to-Case    | —    | —    | 5.0  |       |                      |
| R <sub>th</sub> JA | Junction-to-Ambient |      | _    | 175  | K/W   | Typical socket mount |

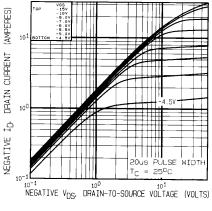


Fig. 1 — Typical Output Characteristics  $T_C = 25^{\circ}C$ 

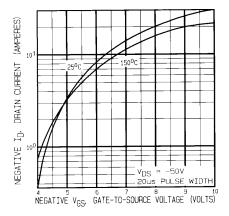


Fig. 3 — Typical Transfer Characteristics

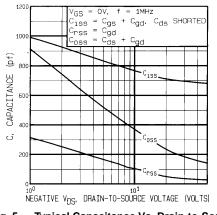


Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage

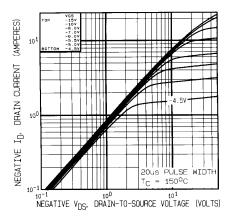


Fig. 2 — Typical Output Characteristics  $T_C = 150^{\circ}C$ 

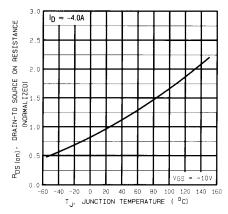


Fig. 4 — Normalized On-Resistance Vs.Temperature

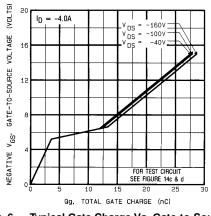
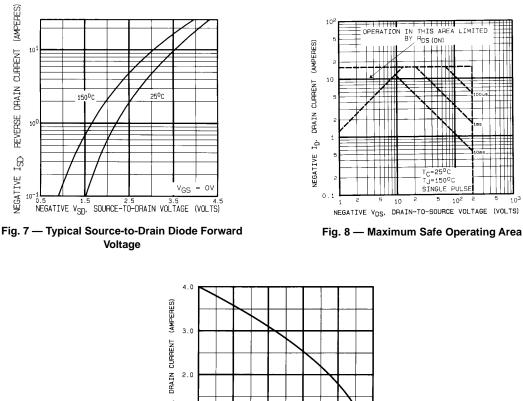
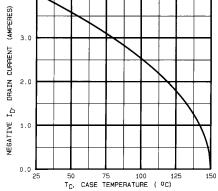


Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage







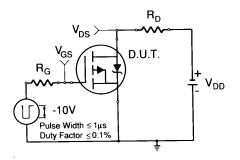
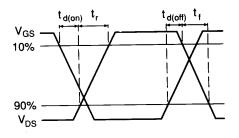


Fig. 10a — Switching Time Test Circuit





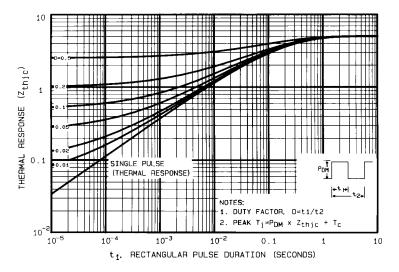


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

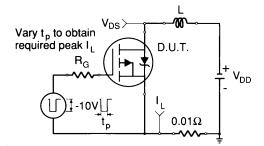


Fig. 12a — Unclamped Inductive Test Circuit

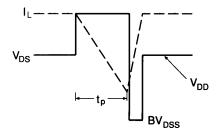


Fig. 12b — Unclamped Inductive Waveforms

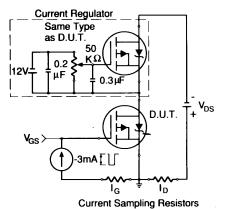


Fig. 13a — Gate Charge Test Circuit

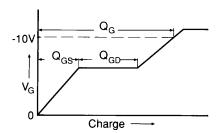
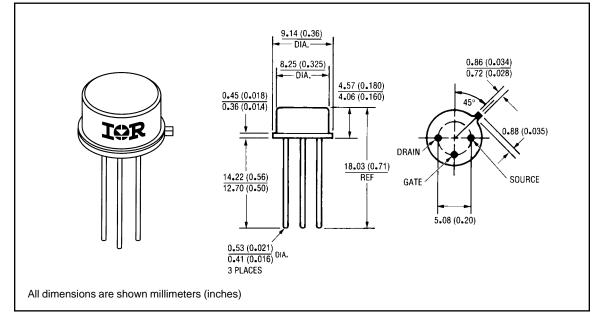


Fig. 13b — Basic Gate Charge Waveform

- Repetitive Rating; Pulse width limited by maximum junction temperature. (see figure 11)
- $\label{eq:VDD} \begin{array}{l} \textcircled{0}{2} & \textcircled{V}_{DD} = \text{-}50\text{V}, \text{ Starting } \textbf{T}_{J} = 25^{\circ}\text{C}, \\ \hline \textbf{E}_{AS} = [0.5 * \texttt{L} * (I_{\texttt{L}}^2) * [\texttt{BV}_{DSS}/(\texttt{BV}_{DSS}\text{-}\texttt{V}_{DD})] \\ \hline \textbf{Peak } \textbf{I}_{\texttt{L}} = \text{-}4.0\text{A}, \ \textbf{V}_{GS} = \text{-}10\text{V}, \ 25 \leq \texttt{R}_{G} \leq 200\Omega \\ \end{array}$

- 3 ISD  $\leq$  -4.0A, di/dt  $\leq$  -120A/µs,
- $V_{DD} \le BV_{DSS}, T_J \le 150^{\circ}C$
- ④ Pulse width  $\leq$  300  $\mu$ s; Duty Cycle  $\leq$  2%
- 5 K/W = °C/W W/K = W/°C

## Case Outline and Dimensions — TO-205AF (TO-39)



# International

WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, Tel: (310) 322 3331 EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, UK Tel: ++ 44 1883 732020 IR CANADA: 7321 Victoria Park Ave., Suite 201, Markham, Ontario L3R 2Z8, Tel: (905) 475 1897 IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590 IR ITALY: Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111 IR FAR EAST: K&H Bldg., 2F, 3-30-4 Nishi-Ikeburo 3-Chome, Toshima-Ki, Tokyo Japan 171 Tel: 81 3 3983 0086 IR SOUTHEAST ASIA: 315 Outram Road, #10-02 Tan Boon Liat Building, Singapore 0316 Tel: 65 221 8371 http://www.irf.com/ Data and specifications subject to change without notice. 10/96